Content

- Corporate Overview
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- Qualification Process
- Manufacturing Process
- Supplier/Technology Selection Strategy, Supply Chain Management
- Quality Overview
- Customer Support
Corporate Identity

- Corporate Overview
  - Click [here](#) for Silicon Labs’ Corporate Overview homepage

- Quality and Environmental Information
  - Highlights
    - ISO Certificates
    - Sony Green Partner Certificate
    - Quarterly Quality & Reliability Report
    - Additional information [here](#)

- Investor Relations, Annual Report and Recent News
  - Click [here](#) for Silicon Labs’ Investor Overview homepage
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New Product Development Major Milestones

Concept & Planning
- Customer
- Sales
- Design & Apps
- Manufacturing

Design
- Analog & Digital
- Software
- Test

Verification
- Applications
- Qualification
- Customer Sampling
- Launch

Production
- Foundry
- Assembly
- Test
- Pack & Ship
Product Development & Release to Manufacturing follows a rigorous process with Management Review & Approval at key milestones

- **Product Development Process**
  - Concept, Architecture, Design and PG (Tapeout) – reviews and checklists at each stage

- **Release to Manufacturing (RTM) Process**
  - Pre-Production > Initial Production > Full Production
    - Formal reviews and checklists at each stage
    - Ship quantity limits increase with each phase

- **RTM addresses the following (not inclusive)**
  - Probe – HW and SW
  - Final Test – HW and SW
  - Qualification
  - Validation & Verification
  - Test Optimization, offshore transfer
  - Cpk and statistical baselines for maverick lot detection
Every design is reviewed to assure robust manufacturability, testability, and cost optimization.

Any risks identified are removed or minimized by methods such as:
- Design changes
- Extra qualification
- Improved manufacturing capability or controls
- Increased monitoring

Reviews are held at the following milestones at a minimum:
- Project approval/Architecture
- Pre-PG
- Initial Production
Test Strategy

- Design for Test Strategy
  - Scan used for synthesized logic
  - Functional test modes employed to isolate functional blocks
  - Built in Self Test (BIST) features also utilized

- Fault Coverage
  - Minimum fault coverage required for production test release

- At Speed Testing
  - Analog, Functional, and Memory tests are tested at datasheet speeds

- Test Insertions
  - Each product is tested at its worst-case temperature at a minimum
  - Promotion to single temperature test from multi-temperature test follows a rigorous process
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Silicon Labs uses industry standard test methods to evaluate products and follows the guidelines of:

- **EIA/JESD 47** - Stress-Test-Driven Qualification of Integrated Circuits
- **AEC-Q100** - Stress Qualification For Integrated Circuits
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Statistical Bin Limits (SBL)

- SBLs are used at these process steps
  - Foundry Wafer Acceptance Test (WAT)
  - Wafer Probe
  - Final Electrical Test

- Limits are established to identify abnormal (maverick) material lots

- Limits are based on overall yields or on specific tests or test groups

- The MRP system automatically places on hold lots that fail to meet limits

- There are two levels of hold/notification
  - Level 1 – Engineering: held for product engineer investigation and validation before release
  - Level 2 – MRB: held for product engineer and quality manager investigation and validation before release
Product Traceability

- Device packages are marked with a product identification number and a tracecode captured in our ERP system.
- Tracecode is also marked on the packing labels.
- Tracecode provides a link to the processing history, from wafer number to shipment.

**EXAMPLE: Si4763-A30-AM**

- Package Type: 40L-QFN-6x6
- Mark Method: Laser
- Logo: None
- Tracecode Type: Standard
- Pin 1 Mark: Circle = 0.90mm diameter (Bottom-Left-Justified)
- Font Size (mm): 0.70mm Right-Justified
- Line 1 Mark Format: Device Number 4763A30
- Line 2 Mark Format: TTTTTT = Mfg Code (from the Assembly PO)
- Line 3 Mark Format:
  - YY = Year of the packaging/assembly start
  - WW = Work Week of the packaging/assembly start
Silicon Labs follows JEDEC as the preferred industry standard

Quality Monitors

- Electrical: production samples are retested to datasheet limits. This sample method identifies defects introduced at the test process step or that have escaped the test process.

- Visual/Mechanical: production is sampled prior to final pack. Inspections coverage includes mark, count, label, cover tape workmanship, moisture barrier bag visual, lead location, part placement, and other workmanship items.

- Reporting: failures drive corrective actions and process/product improvements

- Quality data is reported in quarterly Quality & Reliability Report
Silicon Labs follows JEDEC as the preferred industry standard

- Failure Rate Estimation: A long-term, steady-state failure rate calculation allows circuit and system engineers to allocate failure rates at the component level during system design.

- Failure in Time (FIT): FIT represents the number of failures in a billion hours of operation. Silicon Labs reports FIT rates in its quarterly Quality & Reliability Report as curves and in tables for specific temperatures and assumptions.

- Mean Time To Failure (MTTF): inverse of FIT rate (1/FIT)

- Failure Rate Calculation Method: Long-term failure rates are estimated by applying the Arrhenius equation to data collected from long term operating life tests. Confidence factors of 90% and 60% are reported.
Critical to Quality (CTQ) parameters are controlled by Silicon Labs’ assembly partners.

Their performance is reported quarterly in CpK reports and reviewed by the Silicon Labs Supplier Managers.

<table>
<thead>
<tr>
<th>Process</th>
<th>CTQ Parameter</th>
</tr>
</thead>
<tbody>
<tr>
<td>Wire Bond</td>
<td>Wire pull strength (g)</td>
</tr>
<tr>
<td></td>
<td>Ball shear strength (g)</td>
</tr>
<tr>
<td>Lead plating</td>
<td>Thickness (μ”)</td>
</tr>
<tr>
<td>Saw/Singulation</td>
<td>Package Dimension (mm)</td>
</tr>
</tbody>
</table>
Silicon Labs follows the principles of JEDEC J-STD-046 for change management and notification.

Change Action Boards review and assure compliance for both supplier and internally initiated changes:
- Wafer Fab Changes
- Assembly Changes
- Materials Changes
- Qualification of changes to JEDEC requirements if applicable

Customer Notification:
- PCN – 90 day notification provided to customer
- EOL – 180 for last orders, 360 days for final delivery to customer
- Exceptions require cross-functional review and approval
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Supply Chain Process Overview

- Partner with world-class suppliers
- Manage products from development to customer delivery
- Support unexpected surges in demand
- Reliable, high volume supply
- Quality-centered assembly and test
- Dual sourced for capacity assurance
- ISO9001/14001, certified company and conforms to IATF 16949
Global Supply Chain

- **Wafer Fab**
  - Taiwan
  - China
  - USA
  - Europe
  - Singapore

- **Bump / Probe**
  - Taiwan
  - China
  - Malaysia

- **Assembly / Test**
  - Taiwan
  - Korea
  - Malaysia
  - Thailand
  - China
  - Singapore
  - Philippines

- **Drop Ship**
  - Taiwan
  - Korea
  - China
  - Malaysia
  - Thailand
  - Singapore
  - USA

- **Customers**
  - >20k customers
  - >20 distributors
  - Distributors
  - Direct customers
  - Hubs
IC Manufacturing Model - Fabless and Outsourced

- **FAB**: TSMC, SMIC & others
- **ASSEMBLY**: ASE, SPIL & others
- **TEST & SHIP**: ASE, KYEC & others

100% outsource

>90% outsource
Module Manufacturing Model – Outsourced Assembly

Components

- Silicon Labs ICs & Third Party Suppliers

PCB ASSEMBLY

- Delta, CDTech, Ryder, USI & others

TEST & SHIP

- Contract Manufacturers and Silicon Labs Intl.

>90% outsource

100% outsource

>90% outsource
Supplier & Technology Selection

- Process technology, package choice and test platforms are carefully chosen based on:
  - Technology availability and maturity at suppliers
  - Technology roadmap of suppliers
  - Technology reliability of suppliers
  - Past and present execution (quality, cycle time, deliveries, operational efficiencies) from suppliers
  - Material cost from the supplier and
  - Cost of doing business with that supplier

- Technology choices are made during development phase

- Silicon Labs provides a second source when appropriate to ensure continuity of supply
Supplier Management

- Asia-based Assembly and Test Supplier Management
  - Provides Supplier initial Evaluation, Selection, and on-going Assessment
  - Performs Semiannual Strategic Business Reviews (SBRs) with key suppliers to review overall business, market trends, performance, cost reduction, capacity plans, product roadmaps and specific projects

- Austin-based Foundry Engineering manages the above for the wafer fab suppliers

- Key Suppliers are audited at least annually
  - Quality management systems (ISO 9001 and IATF 16949)
  - Environmental, Health & Safety (including ISO 14001)
  - Social Accountability (RBA (formerly EICC) Code of Conduct)
  - Business parameters (delivery, cost, service, capacity)
  - Technology
  - Self assessment from a supplier is occasionally deemed adequate
Supplier Quality Assurance Monitoring Process

**Outsourcing of Manufacturing Process Quality Assurance**

**Wafer Fab & Sort**
- Defect Density
- FMEA / Control Plan
- In-coming Material Control
- SPC Monitoring
- Cpk Data Analysis
- Wafer Sort Probe Yield Monitoring
- Wafer Reliability Monitoring

**Assembly**
- DOE
- FMEA / Control Plan
- In-coming Material Control
- SPC Monitoring
- Cpk Data Analysis
- Critical to Process / Product Monitoring
- Assembly Yield Monitoring
- Reliability Monitoring

**Final Test**
- Product Characterization
- FMEA / Control Plan
- Test Program / Revision Control
- SPC Monitoring
- Test Yield Monitoring
- QA Electrical Gate ppm
- Reliability Monitoring

**Pack & Ship**
- Outgoing Visual Mechanical Gate ppm
- FMEA / Control
- Shipping Label Information Accuracy
Silicon Labs conducts formal, monthly forecast meetings
- Distributors/Sales/Representatives required to give 12-month rolling forecast secured from Customers

Forecast provides base line for Silicon Labs supply chain
- Drives material starts, such as wafer
- Triggers capacity planning activities
- Identifies gaps in supply / demand
- Provides demand snap-shot for inventory management
- Provides supply / demand snap-shot for product / process management (e.g., PCN planning)

Supplier commitments input into the planning system
- Commitment is measured to On Time Delivery to First Commit Date in SAP

Real-time B2B process flows with key Suppliers and Distributors
Demand/Supply Performance

- **Demand**
  - Demand monitoring performed on an on-going, daily basis
  - Review of backlog against the build plan
  - Build plan adjustments made in real time to manage changes at the Customer/part level

- **Supply Chain Metrics**
  - On time delivery to the Customer Requested Dock Date
  - On time delivery to the First Commit Date
  - Units committed vs. units produced
  - Cycle time
  - Early warning (Planned Finish Date <> Scheduled Commit Date)
Silicon Labs Distribution Support

- Receive weekly POS reports from Distributor
  - Includes shipments, backlog and forecast
- Monitor inventory at Distributor monthly
- Daily/Weekly communication with Distributor on current issues
- Provide latest delivery dates to Distributors on demand via reporting portal
Supply Chain Process Overview

Planning

Monthly

- Demand Plan Consensus
- Manufacturing Requirements
- Supply / Demand Review

Customer Allocation

Supply Disconnects

Operations Plan

Revenue and Shipment Plan (Units, $)

Execution

- Trigger Wafer start
  - Monthly Execution
  - Weekly Execution
- Factory Schedules
- Order Scheduling
- Assembly
- Test
- Backlog

- Inventory
- Orders
- Delivery Commitments

Customer

CDP

SCP

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Packing & Labeling

- Packing media available: tape & reel, tray and tube

- All finished goods are packed in a vacuum sealed Moisture Barrier Bag (MBB), including a Humidity Indicator Card (HIC) and desiccant

- Labels are automatically printed from the ERP System (SAP)

- Handling Units (HUs) may **not** contain more than two Batches

<table>
<thead>
<tr>
<th>Reel / MBB Inner Box / HU Label</th>
<th>Outer Box Shipping Label</th>
</tr>
</thead>
<tbody>
<tr>
<td>Customer or Silicon Labs P/N</td>
<td>Supplier Address</td>
</tr>
<tr>
<td>Handling Unit #</td>
<td>Customer Address</td>
</tr>
<tr>
<td>Date Code / Trace Code</td>
<td>Customer or Silicon Labs P/N</td>
</tr>
<tr>
<td>Seal Date</td>
<td>Handling Unit #</td>
</tr>
<tr>
<td>Assembly Country</td>
<td>Assembly Country</td>
</tr>
<tr>
<td>Quantity</td>
<td>Quantity</td>
</tr>
<tr>
<td>MSL, Reflow Temperature, Bake Time, RoHS, “HF” and “Pb-Free” (if applicable) &amp; Plating Type (e#)</td>
<td>“RoHS”, “HF” and “Pb-Free” symbol (if applicable)</td>
</tr>
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Quality & Environmental Systems

- Registered to ISO 9001 since Jun’00 (link)
- Registered to ISO14001 since Dec’06 (link)
- Certified Sony Green Partner since Aug’08 (link)

Quality Policy
Silicon Labs is committed to total customer satisfaction by:
- Providing differentiated products, solutions and services for a more connected world
- Exceeding customer needs through innovation and simplicity
- Continually improving our world-class quality management system

Environmental Policy
At Silicon Labs, we manage environmental matters as an integral part of our business by our commitment to:
- Designing, marketing, and selling environmentally friendly products,
- Continually improving our environmental performance and pollution prevention,
- Complying with applicable legal and other requirements that relate to our environmental aspects, and
- Minimizing the negative environmental impact of our business activities.
Quality Organization

**Department Head**
- VP of Quality & Central Engineering
  - Director of Quality & Corporate Test Engineering
    - Quality Engineering Director
      - Quality & Environmental Systems Manager
      - Supplier & Asia Quality Manager
      - Device Analysis Lab Manager

**Location**
- Austin
- Singapore
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Customer Support – Analysis & Response

- Corrective Action & Continual Improvement
  - Based on the Eight Discipline (8D) methodology

- World Class In-House FA lab
  - Decap, SEM, FIB capabilities
  - Cooperative with supplier FA capabilities as needed

- Standard FA and 8D response times
  - Initial Failure Analysis: 2 workdays from suspect product receipt
  - 8D Containment: 5 workdays from customer notification or proof of failure (after Initial FA)
  - Final Failure analysis: 12 workdays after Initial Failure analysis
  - 8D Root Cause and Corrective Action Plan: 14 workdays from customer notification or root cause discovery (after Final FA)
Customer Support – DA Lab Capabilities

Facility: 1580 sq.ft.

Imaging Equipment
- 2 High Power Optical Microscopes (1 with confocal capability)
- 2 Low Power Stereo Zoom Microscopes
- Image capturing HW/SW for above
- Dual Beam FIB; FEI Helios Nanolab 660
- Jeol 7600 FE-SEM (750 KX max) with EDAX EDS System
- GE Micromex X-ray with CT capability
- OKOS Scanning Acoustic Microscope (C-SAM)
- Zygo Nexview Optical Surface Profiler

Deprocessing
- Reactive Ion Etcher
- Ion Wave 10 Plasma Etcher
- 3 Polishing/Cross-section Stations and ASAP backside milling machine
- Wet Lab with Chemicals, 2 exhausted Chemical Hood, etc.

Debug
- 3 u-Probe Stations with HP Semiconductor Curve Tracers and miscellaneous bench equipment
- QFI Scanning Optical Laser (1064nm & 1340nm)
- QFI Photo Emission Si-CCD (500nm –1000nm)
- QFI MWIR-512 Thermal Camera
- Multiprobe AFM Nanoprober
- Optotherm Thermal Camera

ESD Characterization and Qualification
- Barth Transmission Line Pulse Tester
- 2 MK2 ESD and Latchup Testers
- Orion CDM Tester
- HPPI VF-TLP Tester
Customer Support – Materials Data

Self-Serve Part Homogeneous Materials Data

Location: [www.silabs.com/quality](http://www.silabs.com/quality)  
(requires registration and login)

After registration, you can access:

- RoHS, Halogen-free, PFOS/PFOA and REACH quick results and Certificates of Compliance
- Downloadable Material Declaration Data sheets (Acrobat pdf sheet or IPC 1752 class 6 XML format)
- Downloadable Homogeneous Materials test results
Several categories of frequently asked questions and answers can be found at www.silabs.com/quality including:

- **Corporate** (e.g. Governance, Locations, Financials)
- **Product** (e.g. Qualification, Traceability, Reporting)
- **Environmental** (e.g. Substance Database, Awards)
- **Quality** (e.g. Failure Analysis, 8Ds, ISO Registrations)
- **Operations** (e.g. Logistics, Supplier Management, Ordering)
Thank you!

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